

# TDS TECHNICAL DATA SHEET

# PANEL BONDING ADHESIVE

| GENERAL |                              |
|---------|------------------------------|
| CODE    | DESCRIPTION                  |
| PBA195  | Panel bonding adhesive 195ml |



## DESCRIPTION

Panel bonding adhesive is a two-component structural epoxy adhesive system intended for use in metal and composite panel bonding. Bond line thickness is controlled by 0,25mm glass beads comprised in the adhesive.

The 2:1 adhesive system is available in either 50ml, 220ml side by side or 195ml universal cartridge format. The universal cartridge can be used with a 1-k caulking gun with high trigger ratio (recommended 26:1)

## FEATURES AND BENEFITS

- Room Temperature curing, heat acceleration possible
- Long open time of 60 min, handling within 4 hours @ 23°C, full cure in 24 hours
- Bond line thickness is controlled by 0,25mm glass beads
- Withstands automotive e-coat, powder prime, and paint oven temperatures up to 230°C
- Spot-weldable (uncured!)
- Excellent corrosion protection
- High energy absorption and very good crash performance

#### NOMINAL COMPONENT PROPERTIES

|                        | (A-Part)      | (B-Part)      |
|------------------------|---------------|---------------|
| Chemistry              | Ероху         | Amine         |
| Colour                 | Black         | Tan           |
| Consistency            | Viscous Paste | Viscous Paste |
| Specific Gravity, g/ml | 1,08          | 1,13          |
| Ratio by Weight        | 1,9           | 1,00          |
| Ratio by Volume        | 2,0           | 1,00          |
| Odor                   | none          | Slight amine  |

#### **TYPICAL CURE CHARACTERISTICS , OF THE MIXED ADHESIVE**

| Open time     | @ 23° C | 60 min   |
|---------------|---------|----------|
| Working time  | @ 23° C | 90 min   |
| Handling time | @ 23° C | 4 hours  |
| Full cure     | @ 23° C | 24 hours |



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**Open Time** also "wet time" or "pot life". The time the adhesive is wet enough to bond to a second substrate being mated in the bed of adhesive. The open time is temperature depending. All data given was measured at 23°C.

Working Time During working time the already joined part can still be re-positioned. Do not take the bonded assembly apart.

**Handling Time** Time when the adhesive is hard enough to hold on its own. The handling strength of freshly bonded parts depends on type and height of outside forces, that impact the bond. Typically 0.75 to 1MPa is needed. In all cases peel forces, that effect the bond need to be reduced as far as possible. The part needs to be clamped or fixed until ha dling strength is reached.

#### PHYSICAL PROPERTIES OF THE CURED ADHESIVE

|                                  | Value        | Test Method  |
|----------------------------------|--------------|--------------|
| Tensile strength, MPa @ 23°C     | 30           | ASTM D-638   |
| Young's Modulus, MPa @ 23°C      | 4550         | ASTM D-638   |
| Elongation, %                    | 3            | ASTM D-638   |
| Poisson Ratio, @ 23°C            | 0,28         | ASTM E-132   |
| Water Absorption, %              | 2,9          | ASTM D-570   |
| Shore Hardness, D                | 80           | ASTM D-2240  |
| CLTE, 10-6/°C @ -30°C to 0°C     | 67           | ISO MAT-2208 |
| CLTE, 10-6/°C @ 100°C to 130°C   | 155          | ISO MAT-2208 |
| Glass Transition Temperature, °C |              |              |
| G' Onset                         | 49           | ASTM E-1640  |
| G" Peak                          | -80, -50, 57 | ASTM E-1640  |
| Tan Delta Peak                   | -80, -49, 73 | ASTM E-1640  |

Physical properties are values, based on material tested in our laboratories, but are subject to a standard deviation from sample to sample. Typical values should not be construed as a guaranteed analysis of any specific lot.

#### **APPLICATION GUIDE**

| Cure                                  | Ambient or heat accelerated cure (max 150°C) |
|---------------------------------------|--|
| Optimum Bondline Thickness            | 0,25mm (glass bead incorporated)             |
| Paint Bake                            | up to 230°C                                  |
| Gap Filling                           | Very Good                                    |
| Sag Resistance                        | For vertical applications                    |
| Consumption, 1/4" Diameter Round Bead | app 35g / m                                  |
| Consumption, 1/2" Diameter Round Bead | app 141g / m                                 |

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SURFACE PREPARATION

| Substrate                  | Surface preparation -<br>Ambient Cure | Surface preparation -<br>Heat Cure |
|----------------------------|---------------------------------------|------------------------------------|
| Metal                      | Abrasion & Degreasing                 | Abrasion & Degreasing              |
| Composite (SMC, RTM, CFRP) | Abrasion                              | Solvent wipe                       |

#### LAP SHEAR STRENGTH

| Substrate                           | Lap Shear Value [MPa] | Failure Mode            |
|-------------------------------------|-----------------------|-------------------------|
| Cold Rolled Steel (1,5mm)           | 27,8                  | Cohesive Failure        |
| Cold Rolled Steel (0,8mm)           | 23,7                  | Steel Deformation       |
| Hot Dipped Galvanized Steel (0,7mm) | 12,6                  | Steel Deformation       |
| Alloyed Galvanized Steel (0,7mm)    | 18,5                  | Cohesive Failure        |
| 6111 Aluminium Alloy (0,9mm)        | 11,3                  | Mixed Failure (COH/ADH) |
| 5052 Aluminium Alloy (0,6mm)        | 12,4                  | Mixed Failure (COH/ADH) |
| ABS                                 | 3,0                   | Substrate Failure       |
| SMC                                 | 8,8                   | Substrate Failure       |

Test Conditions: preparation: Solvent wipe, Orbital Abrasion (80rgd), Bond Line: 0,25mm, Cure: 1w@23°C, Test temperature: 23°C, Crosshead speed: 13mm/min

### HANDLING

Panel bonding adhesive contains ingredients which could be harmful if improperly handled. Contact with skin and eyes should be avoided and necessary protective equipment and clothing should be worn.

Material Safety Data Sheets contain health and safety information for your development of appropriate product handling procedures to protect your employees and customers.

## PACKAGING

Panel bonding adhesive is supplied in cartridges of 195ml.

### SHELF LIFE

Panel bonding adhesive have a shelf life of 24 months from date of filling, when stored indoors between 15° to 32°. After dispense the used mixer should be left attached to the cartridge to ensure sealing from humidity.

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